



STAN RUBINSTEIN ASSOC., INC. 56 LEONARD STREET, #2 FOXBORO, MASSACHUSETTS 02035
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LEAD-FREE ALLOYS

96.5% Tin/3.5% Silver & 96% Tin/4% Silver

Technical Data Sheet

FEATURES

- ❖ Excellent resistance
- ❖ Excellent solder joint reliability
- ❖ High Purity
- ❖ Compatible with most flux types
- ❖ Mfg. to J-Std-006

FLUX COMPATIBILITY

Tin/Silver Alloys are compatible with most major electronic grade fluxes on the market today, and are available in paste and wire form in no-clean, water soluble and rosin chemistries.

Typical Impurity Levels in Percent

Al: <0.003	Au: 0.05	Cd: <0.001	Fe: 0.01	In: <0.01
As: <0.01	Bi: 0.01	Zn: <0.001	Ni: <0.003	Pb: <0.05

TEMPERATURE REQUIREMENTS

APPLICATION	RECOMMENDED TEMPERATURE
REFLOW SOLDERING	PEAK TEMPERATURE 240 – 250 C (464 – 482 F)
WAVE SOLDERING	POT TEMPERATURE OF 260 C (500 F)
HAND SOLDERING	TIP TEMPERATURE OF 355 – 410C (700 – 800F)

STORAGE & SHELF-LIFE

When stored properly these alloys have no limited shelf life. Surface oxidation is cosmetic and will not impede product performance.

SAFETY

- ❖ Use with adequate ventilation and proper personal protective equipment.
- ❖ Refer to the Material Safety Data Sheet for any specific emergency information.
- ❖ Do not dispose of any hazardous materials in non-approved containers.

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